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(54) TRANSVERSELY-EXCITED FILM BULK (52) U.S. Cl. ACOUSTIC RESONATOR FABRICATION CPC H03H 9/02133 (2013.01); H03H 9/02157 USING A PIEZOELECTRIC PLATE, SILICON (2013.01); H03H 9/02015 (2013.01); H03H SUBSTRATE AND HANDLE WAFER 9/02228 (2013.01); H03H 3/02 (2013.01); **H03H 9/568** (2013.01)

(71) Applicant: Resonant Inc., Austin, TX (US)

Inventors: **Kuan Zhang**, Goleta, CA (US); Andrew Kay, Provo, UT (US); Albert Cardona, Santa Barbara, CA (US); Chris O'Brien, San Diego, CA (US)

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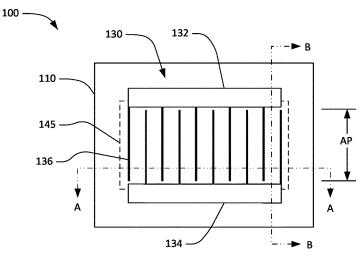
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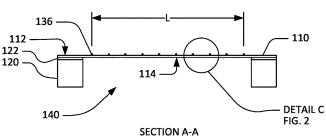
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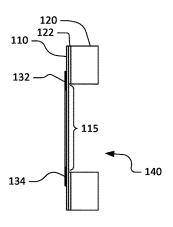
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(57) ABSTRACT

An acoustic resonator device is formed that reduces a thermal coefficient of expansion mismatch between a piezoelectric plate and a silicon substrate by bonding the front surface of the silicon substrate having a filled and planarized sacrificial tub to a piezoelectric substrate and thinning the silicon substrate by removing material from a back surface. That back surface is then bonded to a handle wafer having a thermal coefficient of expansion (TCE) closer to a TCE of the piezoelectric substrate than a TCE of the silicon substrate and thinning the piezoelectric substrate to a target piezoelectric membrane thickness to form a piezoelectric plate. A conductor pattern is formed on the thinned piezoelectric plate and the sacrificial tub is removed to form a cavity and release a membrane of the piezoelectric plate using an etchant introduced through holes in the piezoelectric plate.







SECTION B-B